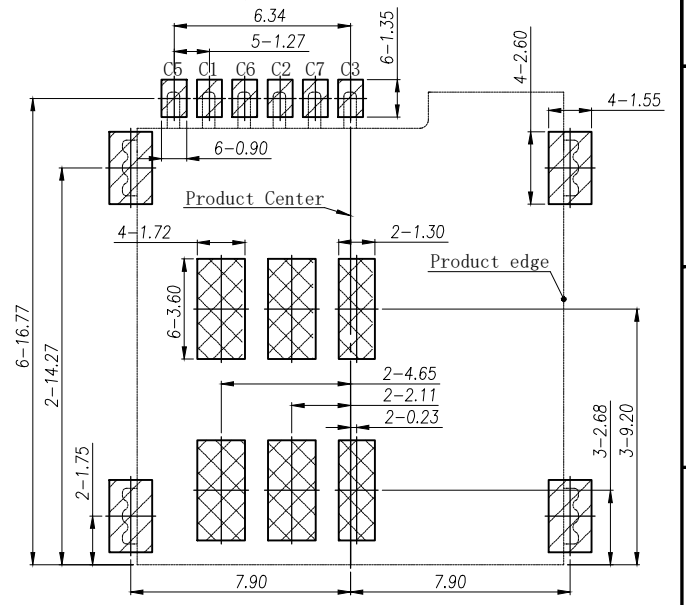
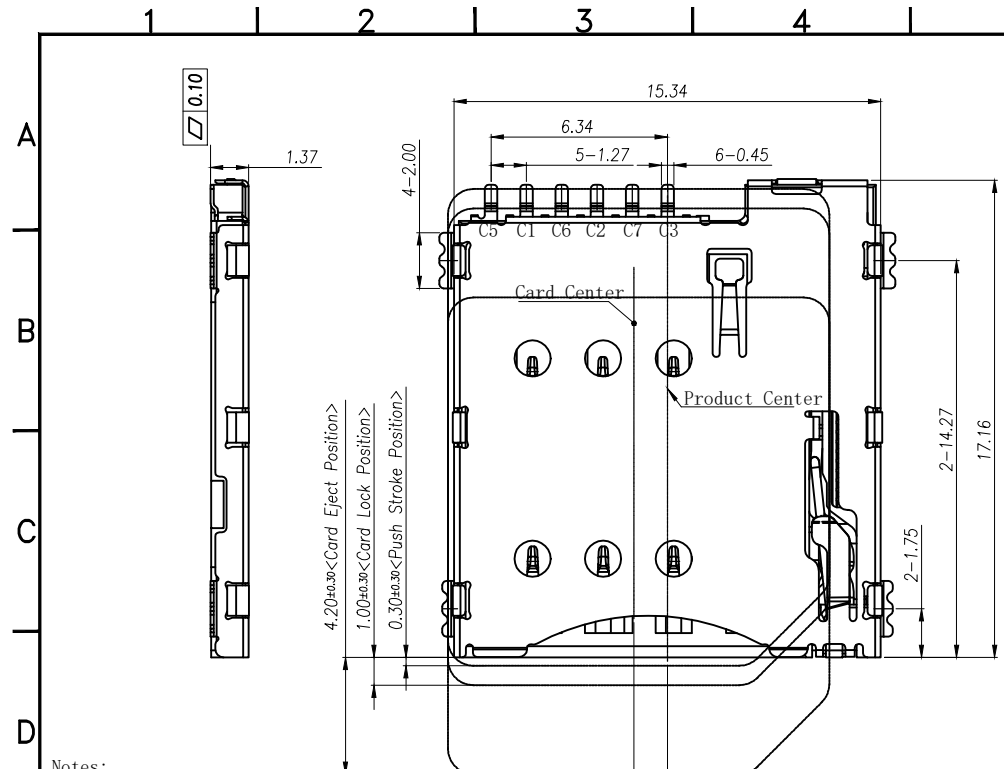


REV.	Q'TY	ECN. NO.	APR.	DATE
A		FIRST RELEASE	Yann	2020.06.12

ROHS

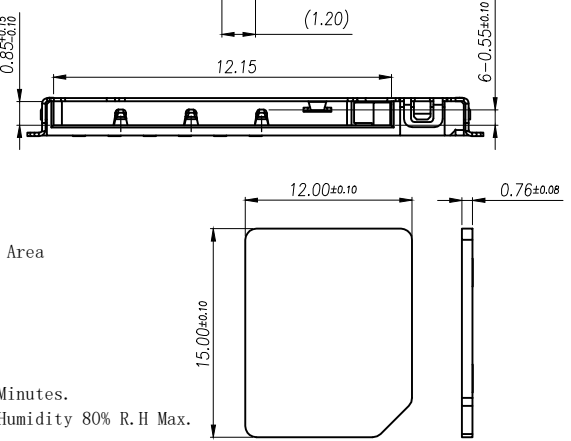


RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)

PIIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

- SMT SOLDER AREA
- COPPER RESTRICTED AREA
- 1.TOUCH AREA OF CONTACT TIPS NO ELECTRICAL FUNCTION
- 2.NO FIRST PCB\_LAYOUT CIRCUITS IN THE AREA

- Notes:
- Material:
    - Housing: High Temperature Thermoplastic
    - Terminal:Copper Alloy
    - Shell: Stainless Steel
  - Plating:
    - Terminal:30u" Ni Underplated Overall
    - G/F Plated On Contact Area
    - 80u" Tin Plated On Solder Area
    - Sheel:30u" Ni Underplated Overall
    - G/F Plated On Contact Area And older Area
  - Technical Speciality:
    - Rated Voltage: 30V
    - Current Rating: 0.5A
    - Insulation Resistance:1000MΩ Min.
    - Contact Resistance:100mΩ Max.
    - Withstanding Voltage: 500V DC For 1 Minutes.
    - Operating Temperature: -40℃~+85℃ Humidity 80% R.H Max.



DONGGUAN JIANXING ELECTRONICS CO., LTD.		Dongguan JianXing Electronics Co.,Ltd.	
TITLE: 1.35H Micro SIM CARD CONNECTOR		DWC NO. SM008-0B135A061	
PROJ.		CUSTOMER DRAWING	
APR.	CHK.	DRA. Yann	REV. A
.X±0.35	.X'± 5'	SIZE A4	SCALE 4:1
.XX±0.25	.X'± 3'	SHEET 1/2	
.XXX±0.15	.XX'± 1'		

